

ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = Top Overlay

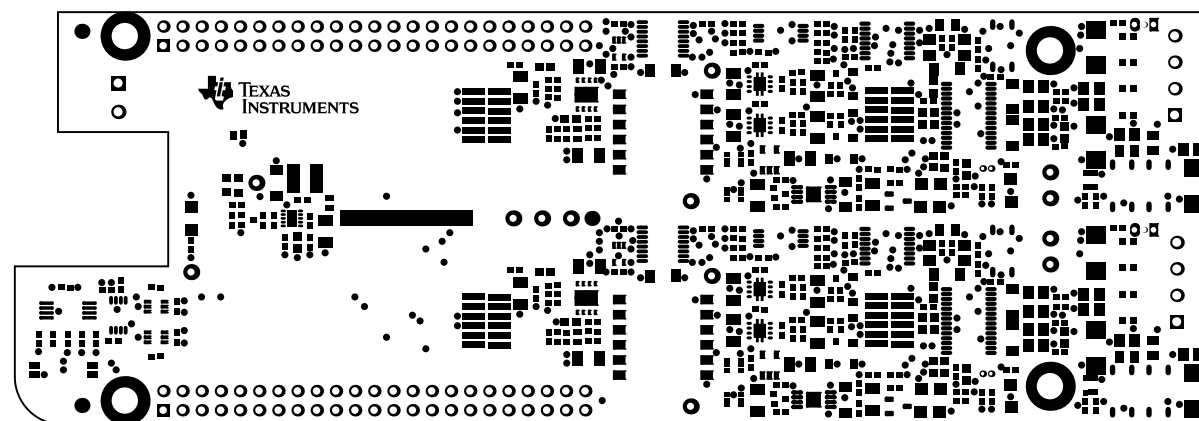
PLOT NAME = Top Overlay

BOARD #: TIDA-00550 REV: E1 SUN REV: Not In VersionControl

TID #: TIDA-00550

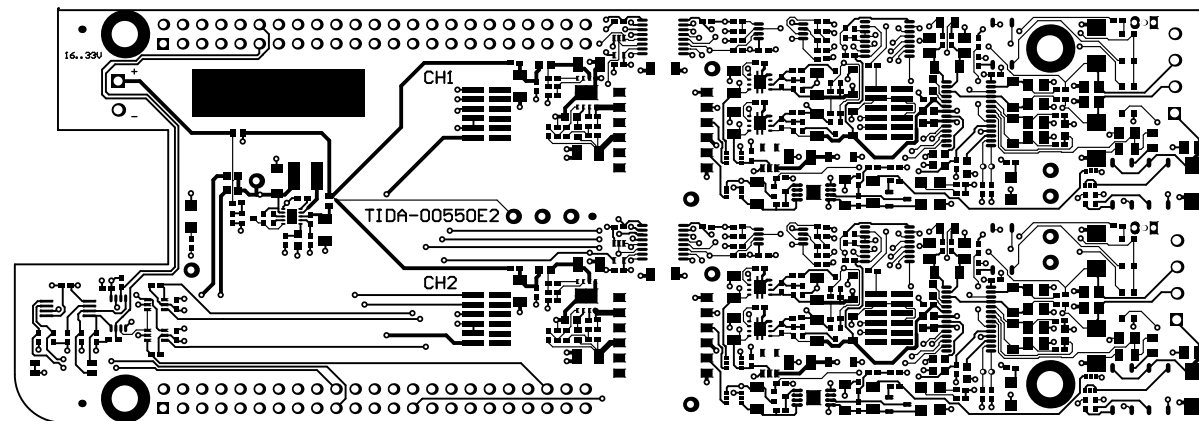
GENERATED : 2/12/2016 2:02:04 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE BOARD #: TIDA-00550 REV: E1 SUN REV: Not In VersionControl
LAYER NAME = Top Solder TID #: TIDA-00550
PLOT NAME = Top Solder Mask GENERATED : 2/12/2016 2:02:08 PM TEXAS INSTRUMENTS

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric 1		8.00mil	4.2	
5	U-	Copper	1.40mil		
6	Dielectric 2	FR-4	40.00mil	4.2	
7	U+	Copper	1.40mil		
8	Dielectric 3		8.00mil	4.2	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = Top Layer

PLOT NAME = Top Layer

BOARD #: TIDA-00550

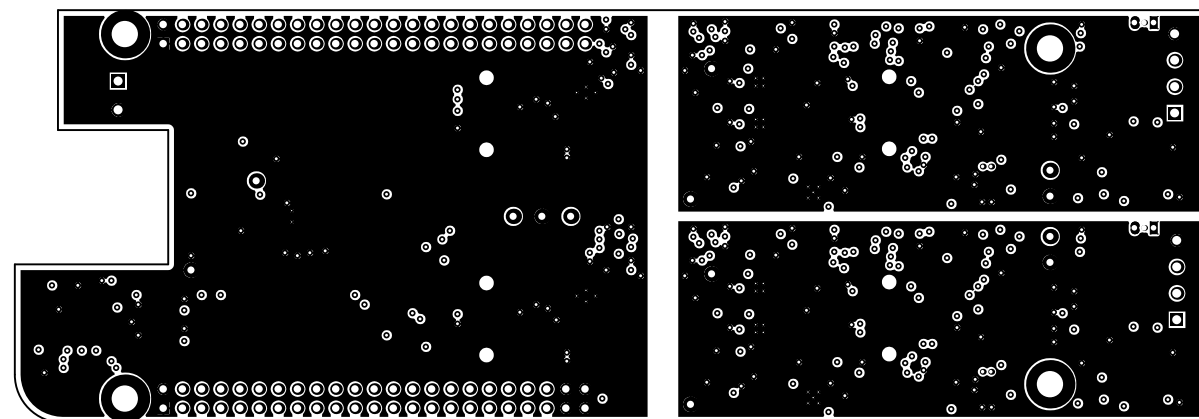
REV: E1

SUN REV: Not In VersionControl

TID #: TIDA-00550

GENERATED : 2/12/2016 2:02:11 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME =

PLOT NAME = Signal Layer 1

BOARD #: TIDA-00550

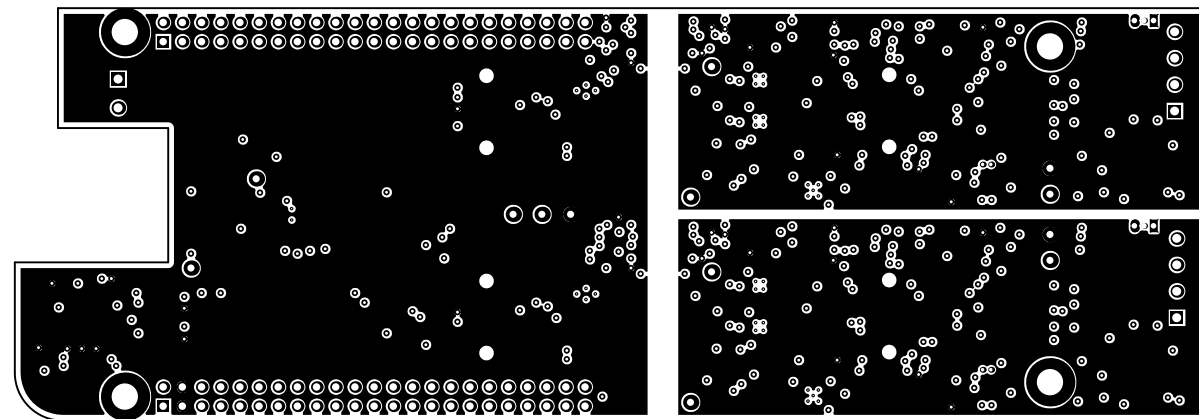
REV: E1

SUN REV: Not In VersionControl

TID #: TIDA-00550

GENERATED : 2/12/2016 2:02:15 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME =

PLOT NAME = Signal Layer 2

BOARD #: TIDA-00550

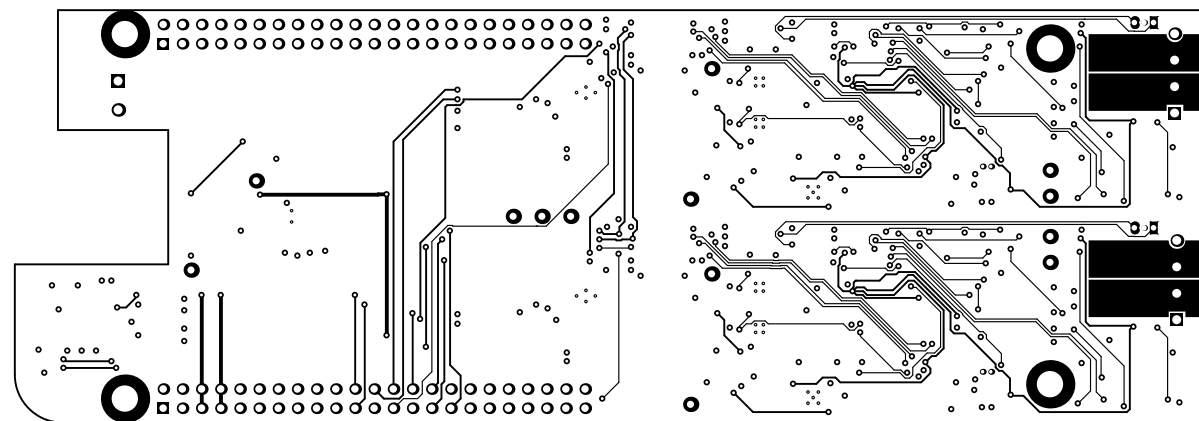
REV: E1

SUN REV: Not In VersionControl

TID #: TIDA-00550

GENERATED : 2/12/2016 2:02:19 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = Bottom Layer

PLOT NAME = Bottom Layer

BOARD #: TIDA-00550

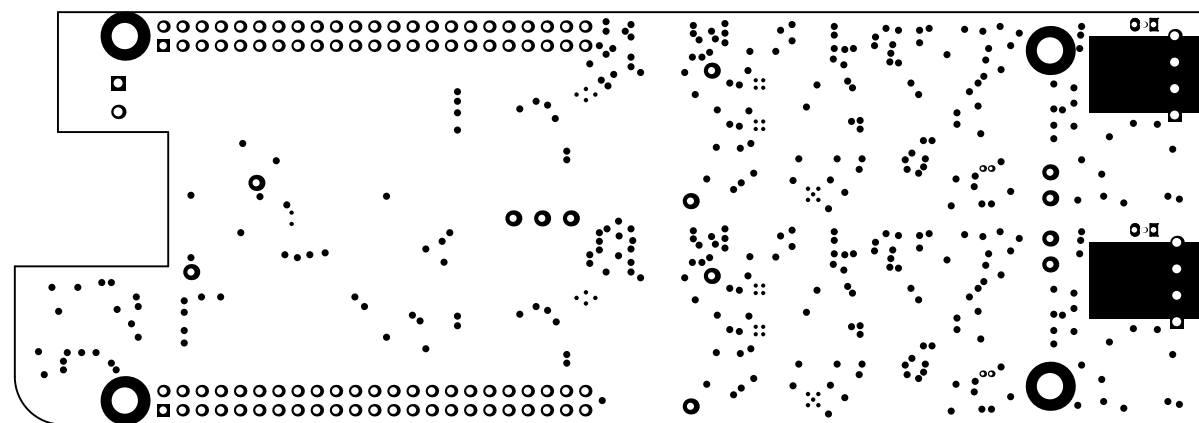
REV: E1

SUN REV: Not In VersionControl

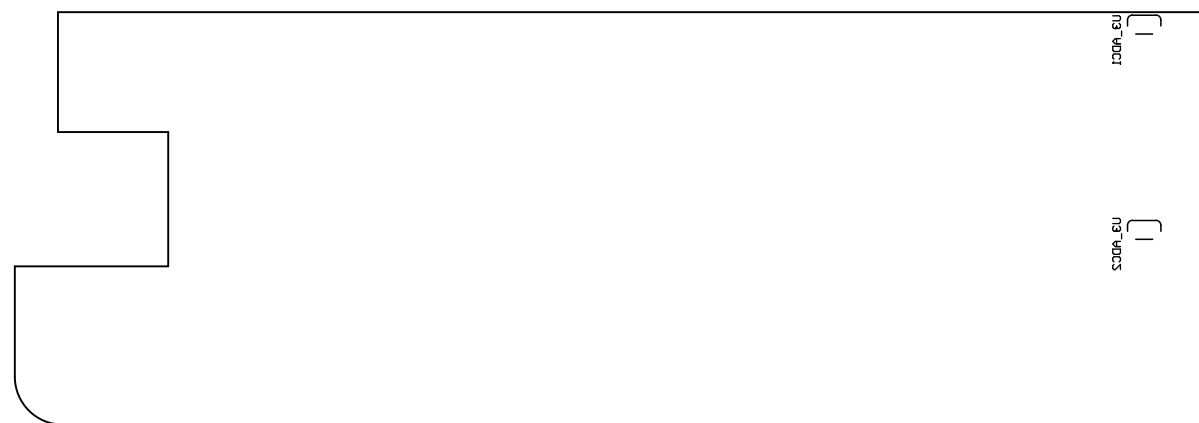
TID #: TIDA-00550

GENERATED : 2/12/2016 2:02:22 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE BOARD #: TIDA-00550 REV: E1 SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder TID #: TIDA-00550
PLOT NAME = Bottom Solder Mask GENERATED : 2/12/2016 2:02:26 PM TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = Bottom Overlay

PLOT NAME = Bottom Overlay

BOARD #: TIDA-00550 REV: E1

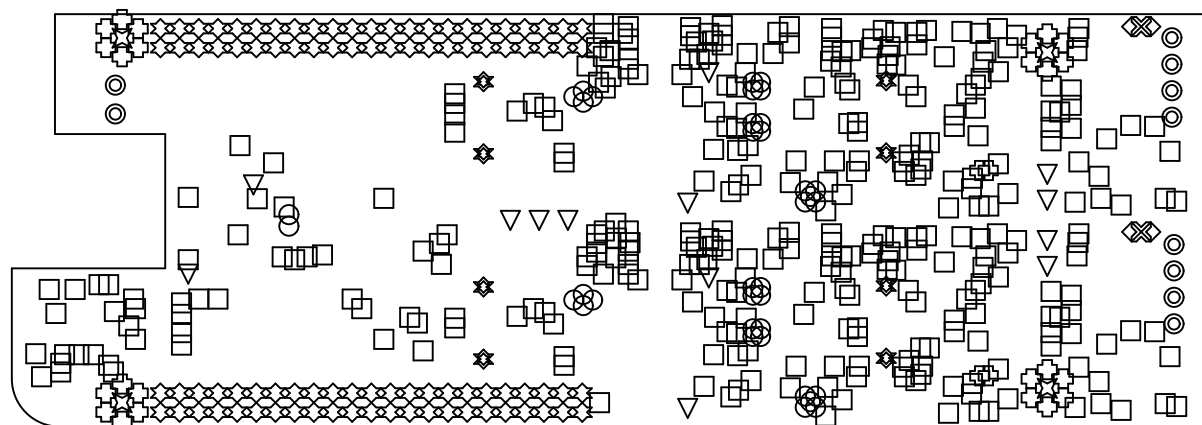
TID #: TIDA-00550

GENERATED : 2/12/2016 2:02:30 PM

SUN REV: Not In VersionControl

TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
⊠	2	29.53mil (0.750mm)	NPTH	Round
✱	8	55.91mil (1.420mm)	NPTH	Round
○	36	7.87mil (0.200mm)	PTH	Round
□	339	16.00mil (0.406mm)	PTH	Round
⊕	28	19.69mil (0.500mm)	PTH	Round
◇	4	29.53mil (0.750mm)	PTH	Round
▽	13	37.99mil (0.965mm)	PTH	Round
✱	92	40.16mil (1.020mm)	PTH	Round
●	10	47.24mil (1.200mm)	PTH	Round
⊠	4	137.80mil (3.500mm)	PTH	Round
	536 Total			



ALL ARTWORK VIEWED FROM TOP SIDE

LAYER NAME = Drill Drawing

PLOT NAME = Drill Drawing

BOARD #: TIDA-00550

TID #: TIDA-00550

GENERATED : 2/12/2016 2:02:34 PM

REV: E1

SUN REV: Not In VersionControl

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE
LAYER NAME = M2 Board Dimensions
PLOT NAME = Board Dimensions

BOARD #: TIDA-00550 REV: E1 SUN REV: Not In VersionControl
TID #: TIDA-00550
GENERATED : 2/12/2016 2:02:37 PM TEXAS INSTRUMENTS

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